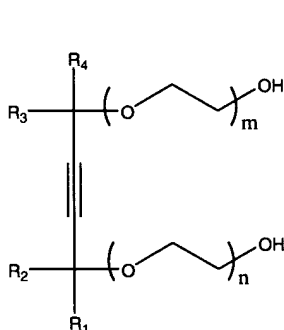


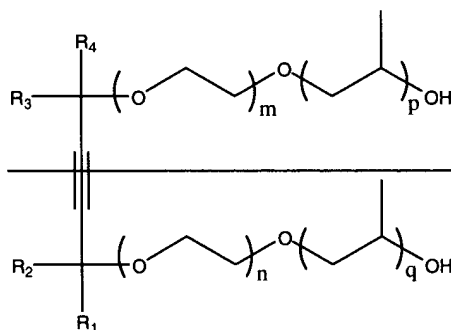
Amendments to the Specification

Please replace paragraph [0021] at page 6 of the specification with the following new paragraph [0021]:

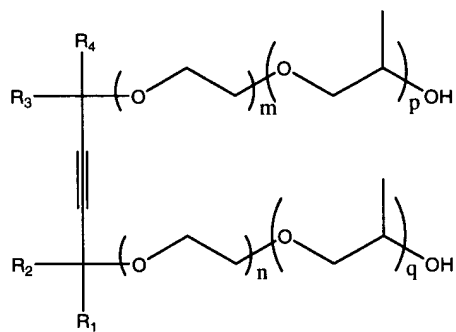
[0021] The present invention satisfies some, if not all, of the needs of the art by providing a process solution and methods for using same. Specifically, in one aspect of the present invention, there is provided a method for reducing defects in the manufacture of semiconductor devices. The method comprises the steps of providing a substrate and contacting the substrate with a process solution comprising about 10 ppm to about 10,000 ppm of at least one surfactant having the formula (I) or (II):



I



II



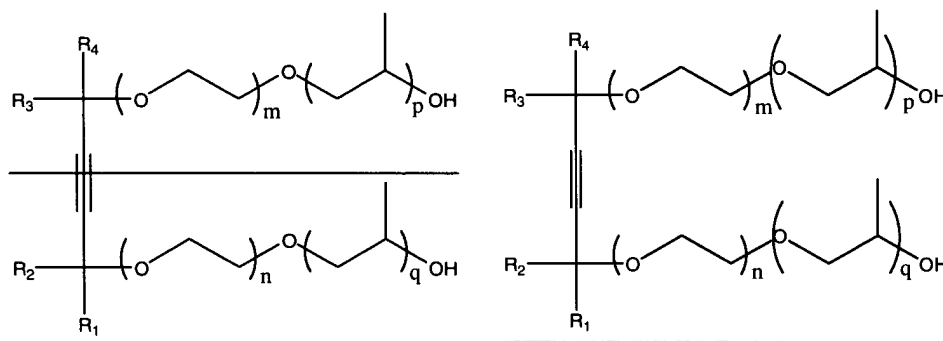
III

wherein R_1 and R_4 are a straight or a branched alkyl chain having from 3 to 10 carbon atoms; R_2 and R_3 are either H or an alkyl chain having from 1 to 5 carbon atoms; and m , n , p , and q

are numbers that range from 0 to 20. In certain preferred embodiments, the process solution further comprises a dispersant.

Please replace paragraph [0022] at page 7 of the specification with the following new paragraph [0022]:

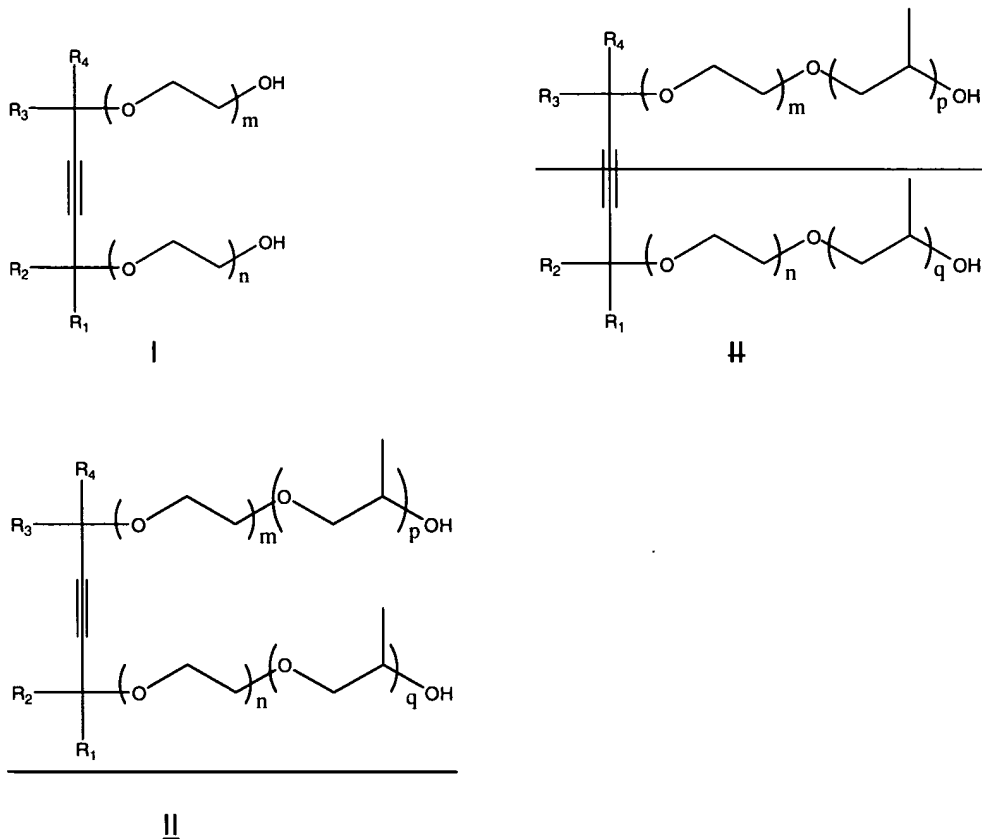
[0022] In a further embodiment of the present invention, there is provided a method for reducing defects in the manufacture of semiconductor devices. The method comprises the steps of providing a substrate and contacting the substrate with a process solution comprising about 10 ppm to about 10,000 ppm of at least one surfactant having the formula:



wherein R_1 and R_4 are a straight or a branched alkyl chain having from 3 to 10 carbon atoms; R_2 and R_3 are either H or an alkyl chain having from 1 to 5 carbon atoms; and m , n , p , and q are numbers that range from 0 to 20. In certain preferred embodiments, the value of $(p + q)$ of the surfactant ranges from 1 to 10.

Please replace paragraph [0023] at page 7 of the specification with the following new paragraph [0023]:

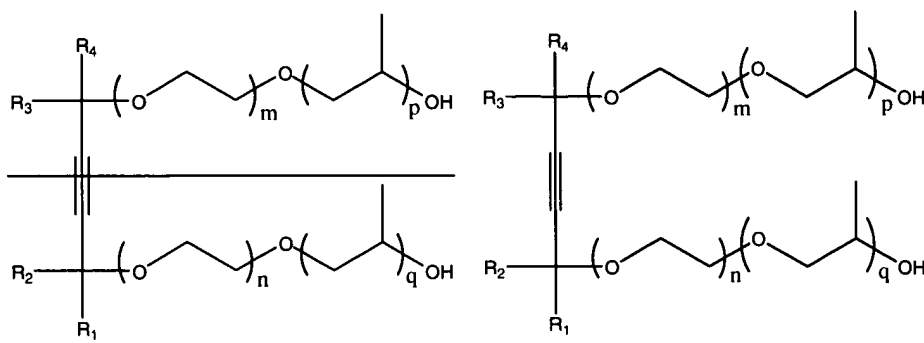
[0023] In yet another embodiment of the present invention, there is provided a process solution having about 10 to about 10,000 ppm of at least one surfactant having the formula (I) or (II):



wherein R₁ and R₄ are a straight or a branched alkyl chain having from 3 to 10 carbon atoms; R₂ and R₃ are either H or an alkyl chain having from 1 to 5 carbon atoms; and m, n, p, and q are numbers that range from 0 to 20.

Please replace paragraph [0024] at page 8 of the specification with the following new paragraph [0024]:

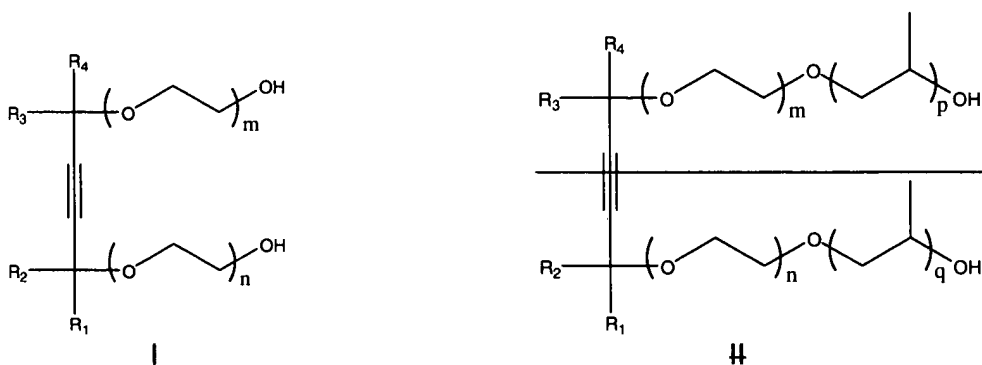
[0024] In a still further embodiment of the present invention, there is provided a process solution comprising about 10 to about 10,000 ppm of a surfactant having the formula:

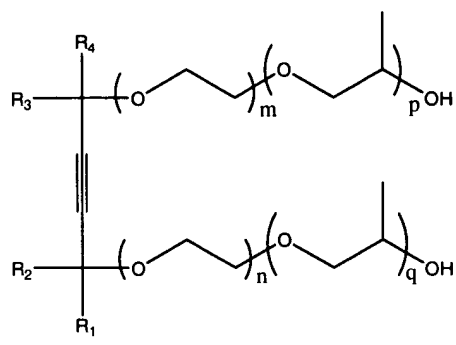


wherein R_1 and R_4 are a straight or a branched alkyl chain having from 3 to 10 carbon atoms; R_2 and R_3 are either H or an alkyl chain having from 1 to 5 carbon atoms; and m , n , p , and q are numbers that range from 0 to 20.

Please replace paragraph [0037] at page 14 of the specification with the following new paragraph [0037]:

[0037] In certain embodiments of the present invention, the process solution may contain one or more nonionic surfactants that are acetylenic diol derivatives. The surfactants of the present invention may be represented by the following formula I or formula II:





II

wherein R_1 and R_4 are each independently a straight or a branched alkyl chain having from 3 to 10 carbon atoms; R_2 and R_3 are each independently a hydrogen atom or an alkyl chain having from 1 to 5 carbon atoms; and m , n , p , and q are each independently a number that ranges from 0 to 20. The surfactants are commercially available from Air Products and Chemicals, Inc. of Allentown, PA, the assignee of the present invention, under the trade names SURFYNOL® and DYNOL®. In certain preferred embodiments, the acetylenic diol portion of the molecule of formulas I or II is 2,4,5,9-tetramethyl-5-decyne-4,7-diol or 2,5,8,11-tetramethyl-6-dodecyne-5,8-diol. The acetylenic diol derived surfactants may be prepared in a number of ways including the methods described, for example, in U. S. Pat. No. 6,313,182 and EP 1115035A1 which are assigned to the assignee of the present invention and incorporated herein by reference in their entirety.